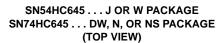
# SCLS304B - JANUARY 1996 - REVISED DECEMBER 2002

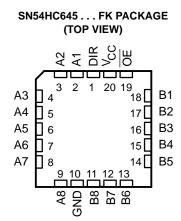
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-µA Max Icc.



_		τ		L
DIR [	1	$\sim$	20	V <sub>CC</sub>
A1 [	2		19	] <u>oe</u>
A2 [			18	] B1
A3 [			17	] B2
A4 [			16	] B3
A5 [			15	] B4
A6 [			14	] B5
A7 [			13	] B6
A8 [	9		12	] B7
GND [	10		11	] B8

#### Typical t<sub>pd</sub> = 12 ns

- ±6-mA Output Drive at 5 V •
- Low Input Current of 1 µA Max
- **True Logic**



SN54HC645, SN74HC645 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPL

#### description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so the buses are effectively isolated.

TA	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING							
	PDIP – N	Tube	SN74HC645N	SN74HC645N							
–40°C to 85°C		Tube	SN74HC645DW	110045							
	SOIC – DW	Tape and reel	SN74HC645DWR	HC645							
	SOP – NS	Tape and reel	SN74HC645NSR	HC645							
	CDIP – J	Tube	SNJ54HC645J	SNJ54HC645J							
–55°C to 125°C	CFP – W	Tube	SNJ54HC645W	SNJ54HC645W							
	LCCC – FK	Tube	SNJ54HC645FK	SNJ54HC645FK							

#### ORDERING INFORMATION

Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
----------------

INP	UTS	
OE	DIR	OPERATION
L	L	B data to A bus
L	н	A data to B bus
Н	х	Isolation



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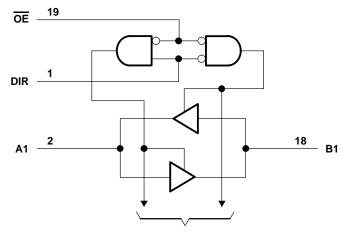


Copyright © 2002, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

### SN54HC645, SN74HC645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCLS304B – JANUARY 1996 – REVISED DECEMBER 2002

### logic diagram (positive logic)



#### **To Seven Other Transceivers**

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>		–0.5 V to 7 V
Input clamp current, $I_{IK}$ (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> ) (see	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC	) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$		±35 mA
Continuous current through V <sub>CC</sub> or GND		±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

			SN54HC645				SN74HC645			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		2	5	6	2	5	6	V	
		$V_{CC} = 2 V$	1.5			1.5				
ViH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V	
		$V_{CC} = 6 V$	4.2			4.2				
		$V_{CC} = 2 V$			0.5			0.5		
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V	
		V <sub>CC</sub> = 6 V			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
VO	Output voltage		0		VCC	0		VCC	V	
		$V_{CC} = 2 V$			1000			1000		
$\Delta t / \Delta v$	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns	
		V <sub>CC</sub> = 6 V			400			400		
TA	Operating free-air temperature	-	-55		125	-40		85	°C	



### SN54HC645, SN74HC645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCLS304B – JANUARY 1996 – REVISED DECEMBER 2002

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

		TEAT OO		N N	Т	A = 25°C	;	SN54H	IC645	SN74H	C645	
PAR	AMETER	TEST CO	NDITIONS	v <sub>cc</sub>	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
				2 V	1.9	1.998		1.9		1.9		
			l <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH		$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			I <sub>OH</sub> = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
				2 V		0.002	0.1		0.1		0.1	
			l <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL		$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
			$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
			I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
Ц	DIR or OE	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
Ioz	A or B	VO = ACC  or  0		6 V		±0.01	±0.5		±10		±5	μA
ICC		$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μA
Ci	DIR or OE			2 V to 6 V		3	10		10		10	pF

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	v	Τ <sub>4</sub>	λ = 25°C	;	SN54H	IC645	SN74H	IC645		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		40	105		160		130		
<sup>t</sup> pd	A or B	B or A	4.5 V		15	21		32		26	ns	
			6 V		12	18		27		22		
			2 V		125	230		340		290		
ten	t <sub>en</sub> OE	A or B	4.5 V		23	46		68		58	ns	
			6 V		20	39		58		49		
			2 V		74	200		300		250		
<sup>t</sup> dis	OE	A or B	4.5 V		25	40		60		50	ns	
			6 V		21	34		51		43		
			2 V		20	60		90		75		
t		A or B	4.5 V		8	12		18		15	ns	
			6 V		6	10		15		13		



### SN54HC645, SN74HC645 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SCLS304B - JANUARY 1996 - REVISED DECEMBER 2002

# switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

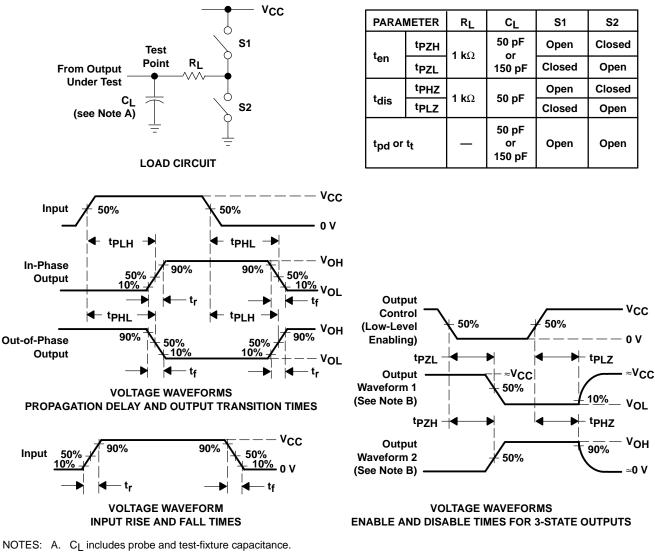
DADAMETER	FROM	то		T <sub>A</sub> = 25°C			SN54H	C645	SN74HC645			
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		54	135		200		170		
<sup>t</sup> pd	A or B	B or A	4.5 V		18	27		40		34	ns	
			6 V		15	23		34		29		
			2 V		150	270		405		335		
<sup>t</sup> en	OE	A or B	4.5 V		31	54		81		67	ns	
			6 V		25	46		69		56		
			2 V		45	210		315		265		
tt		A or B	4.5 V		17	42		63		53	ns	
			6 V		13	36		53		45		

### operating characteristics, $T_A$ = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per transceiver	No load	40	рF



PARAMETER MEASUREMENT INFORMATION



- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tPLH and tPHL are the same as tpd.

#### Figure 1. Load Circuit and Voltage Waveforms





### PACKAGING INFORMATION

Orderable Device	Status	Package Type	-	Pins	-	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN54HC645J	ACTIVE	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54HC645J	Samples
SN74HC645DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC645	Samples
SN74HC645DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC645	Samples
SN74HC645N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC645N	Samples
SNJ54HC645FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54HC 645FK	Samples
SNJ54HC645J	ACTIVE	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54HC645J	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



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#### OTHER QUALIFIED VERSIONS OF SN54HC645, SN74HC645 :

- Catalog: SN74HC645
- Military: SN54HC645

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

### PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION

#### REEL DIMENSIONS

TEXAS INSTRUMENTS





#### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal		
	_	-

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC645DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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### PACKAGE MATERIALS INFORMATION

14-Jul-2012



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC645DWR	SOIC	DW	20	2000	367.0	367.0	45.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

### N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



# **DW0020A**



## **PACKAGE OUTLINE**

### SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



## DW0020A

# **EXAMPLE BOARD LAYOUT**

### SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## DW0020A

## **EXAMPLE STENCIL DESIGN**

### SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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